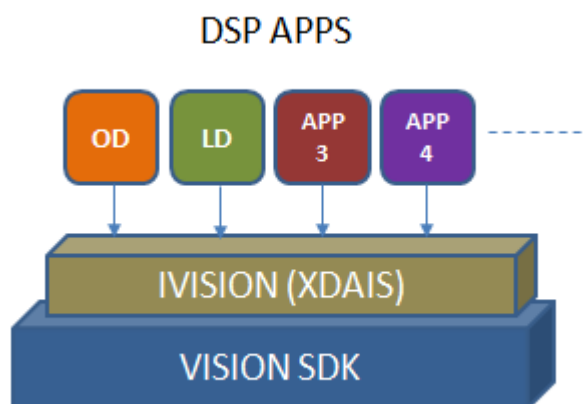


- IVISION (XDAIS) interface compliant
- Validated on TDA2x EVM
- Supports pedestrian detection and traffic sign recognition.
- Tracks upto 32 pedestrians and 32 traffic signs per frame.
- Identifies 43 different types of German traffic signs.
- Supports user controlled parameters to control between accuracy and run time performance
- Supports user controlled thresholds to control the accuracy (False positive vs True Negative)



Description

Object detection module is TI's proprietary Vision and Imaging algorithm implemented on TMS320C66x DSP. Objected detection module is validated with Code Composer Studio version 5.1.0.09000 and code generation tools version 7.4.4.

Performance and Memory Summery

Table 1. Configuration Table

CONFIGURATION	ID
Pedestrian Detection + Traffic Sign Recognition	OBJDET_001
Pedestrian Detection Only	OBJDET_002
Traffic Sign Recognition Only	OBJDET_003

PRODUCT PREVIEW



CONFIGURATION ID	TEST DESCRIPTION	TI C66X DSP PERFORMANCE STATISTICS / FRAME	
		MIN (MHZ)	MAX(MHZ)
OBJDET_001	Resolution = 1280x720, Number of scales/octave = 6 Number of scales/frame= 21 % ROI in base scale = 25% with grow by 1.12 in each successive scale 2x2 block sum done on EVE	21.1	24.3
OBJDET_002		4.9	6.1
OBJDET_003		17.6	19.6
OBJDET_001	Resolution = 1280x720, Number of scales/octave = 6 Number of scales/frame= 21 % ROI in base scale = 20% with grow by 1.12 in each successive scale 2x2 block sum done on EVE	18.6	21.1
OBJDET_002		3.8	4.8
OBJDET_003		15.3	19.6
OBJDET_001	Resolution = 1280x720, Number of scales/octave = 6 Number of scales/frame= 21 % ROI in base scale = 25% with grow by 1.12 in each successive scale 2x2 block sum done on DSP	22.3	25.8
OBJDET_002		6.4	7.4
OBJDET_003		19.0	21.1
OBJDET_001	Resolution = 1280x720, Number of scales/octave = 6 Number of scales/frame= 21 % ROI in base scale = 20% with grow by 1.12 in each successive scale 2x2 block sum done on DSP	19.2	22.0
OBJDET_002		4.9	5.9
OBJDET_003		16.8	18.3

¹ Performance is validated by running on TDA2x platform. DDR-532Mhz, DSP-600Mhz. The scene comprises of 1 pedestrian and 4 traffic signs. The performance of the algorithm will vary depending on the number of objects available in the scene.

Table 2. Memory Statistics - Generated with Code Generation Tools Version 7.4.4

CONFIGURATION ID	RESOLUTION	MEMORY STATISTICS ¹						
		PROGRAM MEMORY	INTER NAL	DATA MEMORY			STACK	TOTAL
				PERSIST ENT	SCRAT CH	CONST		
OBJDET_001	1280x720	72.5	248	519.6	10.6	297.7	6	1154.4
OBJDET_002	1280x720	72.5	169	519.6	10.6	138.4	6	916.1
OBJDET_003	1280x720	72.5	94	519.6	10.6	160.2	6	862.9

¹ All memory requirements are expressed in kilobytes (1 K-byte = 1024 bytes) and there could be a variation of around 1-2% in the numbers.

Table 3. Internal Data Memory Split-up

CONFIGURATION ID	DATA MEMORY – INTERNAL ²		
	SHARED		INSTANCE ³
	CONSTANTS	SCRATCH	
OBJDET_001	199	49	-
OBJDET_002	137	32	-
OBJDET_003	62	32	-

² Internal memory refers to on chip memory. All memory requirements are expressed in kilobytes and there could be a variation of around 1-2% in numbers. L1D memory is split into 24kb of SRAM, 8kb of cache. L2 memory is split as 224kb of SRAM and 64 kb of cache. Executing object detection module along with other DSP algorithm which requires different L1D configuration could hinder performance.

³ I/O buffers are not included. Some of the instance memory buffers could be scratch.

notes

- I/O buffers:
 - Input buffer size = 3481.83 K-bytes (For 1280x720 resolution , 21 scales, 1 frame, 25% ROI)
 - Output buffer size = 16.5 K-bytes (For a maximum of 32 objects per frame)
 - Total data memory for N non pre-emptive instances = Constants + Runtime Tables + Scratch + N * (Instance + I/O buffers + Stack)
- Total data memory for N pre-emptive instances = Constants + Runtime Tables + N * (Instance + I/O buffers + Stack + Scratch)

references

- ObjectDetection_DSP_UserGuide.pdf

glossary

Constants	Elements that go into .const memory section
Scratch	Memory space that can be reused across different instances of the algorithm
Shared	Sum of Constants and Scratch
Instance	Persistent memory that contains persistent information - allocated for each instance of the algorithm

acronyms

DMA	Direct Memory Access
EVM	Evaluation Module

PRODUCT PREVIEW



IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, enhancements, improvements and other changes to its semiconductor products and services per JESD46, latest issue, and to discontinue any product or service per JESD48, latest issue. Buyers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All semiconductor products (also referred to herein as “components”) are sold subject to TI’s terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its components to the specifications applicable at the time of sale, in accordance with the warranty in TI’s terms and conditions of sale of semiconductor products. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by applicable law, testing of all parameters of each component is not necessarily performed.

TI assumes no liability for applications assistance or the design of Buyers’ products. Buyers are responsible for their products and applications using TI components. To minimize the risks associated with Buyers’ products and applications, Buyers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any patent right, copyright, mask work right, or other intellectual property right relating to any combination, machine, or process in which TI components or services are used. Information published by TI regarding third-party products or services does not constitute a license to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of significant portions of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Resale of TI components or services with statements different from or beyond the parameters stated by TI for that component or service voids all express and any implied warranties for the associated TI component or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

Buyer acknowledges and agrees that it is solely responsible for compliance with all legal, regulatory and safety-related requirements concerning its products, and any use of TI components in its applications, notwithstanding any applications-related information or support that may be provided by TI. Buyer represents and agrees that it has all the necessary expertise to create and implement safeguards which anticipate dangerous consequences of failures, monitor failures and their consequences, lessen the likelihood of failures that might cause harm and take appropriate remedial actions. Buyer will fully indemnify TI and its representatives against any damages arising out of the use of any TI components in safety-critical applications.

In some cases, TI components may be promoted specifically to facilitate safety-related applications. With such components, TI’s goal is to help enable customers to design and create their own end-product solutions that meet applicable functional safety standards and requirements. Nonetheless, such components are subject to these terms.

No TI components are authorized for use in FDA Class III (or similar life-critical medical equipment) unless authorized officers of the parties have executed a special agreement specifically governing such use.

Only those TI components which TI has specifically designated as military grade or “enhanced plastic” are designed and intended for use in military/aerospace applications or environments. Buyer acknowledges and agrees that any military or aerospace use of TI components which have **not** been so designated is solely at the Buyer’s risk, and that Buyer is solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI has specifically designated certain components as meeting ISO/TS16949 requirements, mainly for automotive use. In any case of use of non-designated products, TI will not be responsible for any failure to meet ISO/TS16949.

Products

Audio	www.ti.com/audio
Amplifiers	amplifier.ti.com
Data Converters	dataconverter.ti.com
DLP® Products	www.dlp.com
DSP	dsp.ti.com
Clocks and Timers	www.ti.com/clocks
Interface	interface.ti.com
Logic	logic.ti.com
Power Mgmt	power.ti.com
Microcontrollers	microcontroller.ti.com
RFID	www.ti-rfid.com
OMAP Applications Processors	www.ti.com/omap
Wireless Connectivity	www.ti.com/wirelessconnectivity

Applications

Automotive & Transportation	www.ti.com/automotive
Communications & Telecom	www.ti.com/communications
Computers & Peripherals	www.ti.com/computers
Consumer Electronics	www.ti.com/consumer-apps
Energy and Lighting	www.ti.com/energyapps
Industrial	www.ti.com/industrial
Medical	www.ti.com/medical
Security	www.ti.com/security
Space, Avionics & Defense	www.ti.com/space-avionics-defense
Video & Imaging	www.ti.com/video

TI E2E Community e2e.ti.com

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265 Copyright© 2015,
Texas Instruments Incorporated